Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	59	235/492.ccls. and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6))	USPAT	OR	ON	2006/07/31 13:56
S2	201	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6)) and (cut\$6 with module)	USPAT	OR	ON	2006/07/31 13:57
S3	149	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6) with (modul\$4 chip semiconduc\$6)) and (cut\$6 with (module semiconduct\$6))	USPAT	OR	ON	2006/07/31 14:24
S9	182	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet dry\$6 dried melt\$4) with (glue adhes\$6 laminat\$6 paste\$4 bond\$4))	USPAT	OR	ON	2006/08/01 10:02
S10	101	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 laminat\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet dry\$6 dried melt\$4) with (glue adhes\$6 laminat\$6 paste\$4 bond\$4)) and tape	USPAT	OR	ON	2006/08/01 10:06
S13	23	((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:12

S14	25	((wind winding roll\$5 wound\$4 reel\$6) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:22
S15	42	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4)).	USPAT	OR	ON	2006/08/01 10:38
S16	53	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	US-PGPUB	OR	ON	2006/08/01 10:40
S17	2	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 10:41

S18	44	((wind winding roll\$5 wound\$4 reel\$6) with (modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with (module chip semiconduct\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:56
S19	1	"4897534".pn.	USPAT	OR	ON	2006/08/01 10:51
S20	17	((wind winding roll\$5 wound\$4 reel\$6) with (electronic)) and ((cut\$6 punch\$6 stamp\$5 peel\$4) with electronic) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 10:54
521	176	((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/02 08:40
S22	5	"5874142".uref.	USPAT	OR	ON	2006/08/01 11:17
S23	153	((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4))) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	US-PGPUB	OR	ON	2006/08/02 08:14
S24	1405	((wind winding roll\$5 wound\$4 reel\$6) with (tape web)) and ((liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:24

S25	217	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:27
S27	46	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten) with (glue adhes\$6 paste\$4 bond\$4) with (heat\$6 hot\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:32
S28	48	((wind winding roll\$5 wound\$4 reel\$6) with (tape web) with (liquid\$4 wet melt\$4 molten soft\$6) with (glue adhes\$6 paste\$4 bond\$4) with (heat\$6 hot\$4) with (dry\$4 dried solid\$4))	USPAT	OR	ON	2006/08/01 11:38
S29	153	235/492.ccls. and ((wind winding roll\$5 wound\$4 reel\$6) with (electronic modul\$4 chip semiconduc\$6 ic (integrat\$4 adj circuit\$4)))	USPAT	OR	ON	2006/08/02 08:31
S30	32	"4897534".uref.	USPAT	OR	ON	2006/08/02 08:34
S31	27	"5055913".uref.	USPAT	OR	ON	2006/08/02 08:36
S32	9	"5670001".uref.	USPAT	OR	ON	2006/08/02 08:37
S36	55	"438"/\$.ccls. and ((liquid\$4 wet melt\$4 molten soft\$8) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4 hard\$4)) and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4))	USPAT	OR .	ON	2006/08/02 08:55
S37	1	("6924211" "6753614").uref.	ÜSPAT	OR	ON	2006/08/02 08:58
S38	48	"438"/\$.ccls. and ((liquid\$4 wet melt\$4 molten soft\$8) with (glue adhes\$6 paste\$4 bond\$4)) and ((heat\$6 hot\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4) with (dry\$4 dried solid\$4 hard\$4)) and ((wind winding roll\$5 wound\$4) with (glue\$4 adhes\$6 paste\$4 bond\$4))	US-PGPUB	OR	ON	2006/08/02 08:56
S39	2	("6924211" "6753614").pn.	USPAT	OR	ON	2006/08/02 08:58
S40	1	"5030308".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58

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S41	1	"5667073".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58
S42	1	"6103554".PN.	USPAT; USOCR	OR	OFF	2006/08/02 08:58
S43	1	"6412641".PN.	USPAT; USOCR	OR .	OFF	2006/08/02 08:59
S44	646	heat\$6 with (glue\$4 gluing adhesiv\$6) with wound	USPAT	OR	ON	2006/10/18 10:09
S45	165	(heat\$6 with (glue\$4 gluing adhesiv\$6) with wound) and ((solid\$4 hard\$6) with (glue\$4 gluing adhesiv\$6))	USPAT	OR	ON	2006/10/18 11:30
S46	1	reel with (fiberglass with epoxy with resin)	USPAT	OR ·	ON	2006/10/18 11:58
S47	9	reel with (fiber\$4glass with resin)	USPAT	OR	ON	2006/10/18 12:21
S48	114	235/492.ccls. and wound	USPAT	OR	ON	2006/10/18 12:22
S49	3	("6924211" "6753614" "5055913"). pn.	USPAT	OR	ON	2006/10/18 12:24
S50	2	("6924211" "6753614" "5055913"). pn. and cut\$6	USPAT	OR	ON	2006/10/18 12:23
S51	14	235/492.ccls. and (cut\$6 with module with insert\$6)	USPAT	OR	ON	2006/10/18 12:25
S56	46	(wind\$4 wound\$4 roll\$5) with heat\$4 with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty)	US-PGPUB	OR	ON	2007/03/09 12:12
S57	118	(wind\$4 wound\$4 roll\$5) with heat\$4 with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty)	USPAT	OR	ON	2007/03/09 12:38
S59	431	"438"/\$.ccls. and (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty)	USPAT	OR	ON	2007/03/09 12:19
S60	73	"438"/\$.ccls. and (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty) and ((cut\$5 remov\$6 tear\$4 torn\$4) with (strip web\$6 tape\$4 taping))	USPAT	OR ·	ON	2007/03/09 12:20

S61	724	(wind\$4 wound\$4 roll\$5) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty)	USPAT	OR	ON	2007/03/09 12:40
S62	8	"438"/\$.ccls. and ((wind\$4 wound\$4 roll\$5) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty))	USPAT	OR	ON	2007/03/09 12:40
S63	2	"438"/\$.ccls. and ((wind\$4 wound\$4 roll\$5) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty))	US-PGPUB	OR	ON	2007/03/09 12:40
S64	152	(wind\$4 wound\$4 roll\$5) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty) with (high\$4 temperatur\$4)	USPAT	OR .	ON	2007/03/09 12:44
S65	468	(wind\$4 wound\$4 roll\$5) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6 dry\$4 drie\$4) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty) with (high\$4 temperatur\$4 heat\$4 hot\$4)	USPAT	OR	ON	2007/03/09 13:44
S66	515	(wind\$4 wound\$4 roll\$2 rolled roller rolling) with (liquid\$4 wet\$4 semi\$1liquid\$4 soft\$5 tacky) with (solid\$4 hard\$6 dry\$4 drie\$4) with (bond\$4 glue\$4 gluing adhes\$6 adher\$4 paste\$4 pasty) with (high\$4 temperatur\$4 heat\$4 hot\$4)	USOCR	OR	ON	2007/03/09 13:47